



UPBLED470B

HIGH BRIGHTNESS BLUE LED

PRODUCT PREVIEW

Microsemi's high brightness UPBLED470B product offers impressive brightness with industry leading thermal resistivity. These products deliver superior thermal characteristics that keep junction temperatures low with a remarkable package thermal resistivity of 110 degrees C/Watt. The blue packages also deliver a very wide viewing angle able to easily integrate into optical lenses. The Optomite package performs extremely well under extreme temperature conditions with less wavelength shift and intensity degradation seen by many competitors.

IMPORTANT: For the most current data, consult MICROSEMI's website: <http://www.microsemi.com>

ABSOLUTE MAXIMUM RATINGS AT 25° C (UNLESS OTHERWISE SPECIFIED)

| Parameters | Symbol | Value | Unit DC |
|---|------------------|-------------|---------|
| Forward Drive Current | I _F | 30 | mA |
| Peak Forward Current | I _{FP} | 100 | mA |
| LED Operating Junction Temperature | T _J | -40 to +150 | °C |
| Reverse Voltage | V _R | 8 | V |
| Power Dissipation | P _D | 125 | mW |
| Operating Temperature | T _{OPR} | -40 to +125 | °C |
| Storage Temperature | T _S | -45 to +150 | °C |
| Electrostatic Discharge | ESD | 1000 | V |
| ESD classification | | Class 2 | |
| Solder Reflow Peak Temperature (Solder 10") | | 225 | °C |

THERMAL CHARACTERISTICS (UNLESS OTHERWISE SPECIFIED)

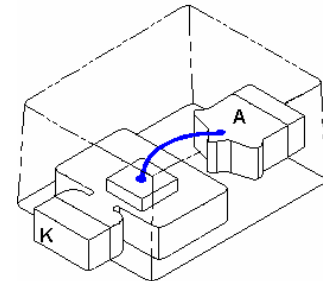
| Thermal Resistance | Symbol | Value | Units |
|-----------------------------|------------------|-------|-------|
| Junction-to Soldering Point | R _{θJS} | 110 | °C/W |

KEY FEATURES

- Low Thermal Resistance
- Rugged Optomite 0603 package
- High Brightness
- Wide viewing angle

APPLICATIONS/BENEFITS

- Mobile Phone Keypad
- Panel, button, switch indicators.
- Backlighting
- Signage
- Signals and Marker Lights



For operation of these LEDs in pulse mode applications, devices may be used in conjunction with the Microsemi LX1992LED Drivers



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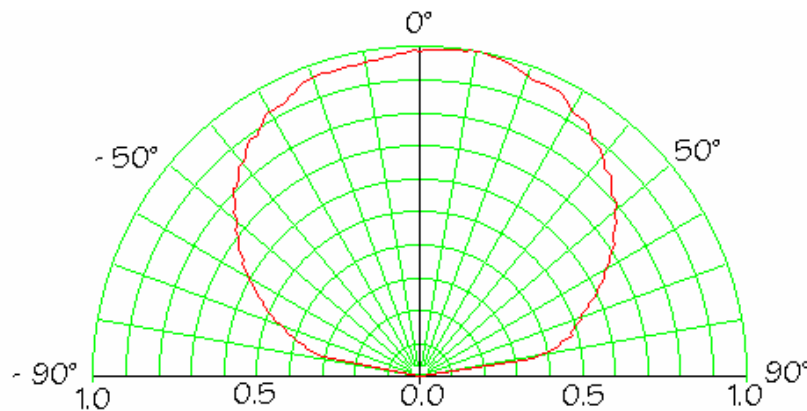
ELECTRICAL PARAMETERS @ 25°C & ID=20 mA (unless otherwise specified)

| Characteristic | Symbol | Test Conditions | Min | Typ. | Max | Units |
|------------------------------|------------------------|--|-----|----------------------|-----|------------------|
| Radiant Intensity | I_E | DC Drive Current = 20 mA DC Drive Current = 30 mA DC Drive Current = 50 mA | | 950 1250 1,600 | | $\mu\text{W/sr}$ |
| Luminous Intensity | I_V | DC Drive Current = 20 mA DC Drive Current = 30 mA DC Drive Current = 50 mA | 50 | 65 75 100 | | mcd |
| Dominant Wavelength | λ_{DOM} | DC Drive Current = 20 mA | | 468 | | nm |
| Peak Wavelength | λ_{PK} | DC Drive Current = 20 mA | | 460 | | nm |
| Chrom x Chrom y | | DC Drive Current = 20 mA | | 0.125 0.09 | | |
| Angle Coverage to 50% points | $\alpha_{1/2}$ | DC Drive Current = 20 mA to 50mA | 140 | | | deg. |
| Radiant Flux | Φ_E | DC Drive Current = 20 mA DC Drive Current = 30 mA DC Drive Current = 50 m | | 2.5 3.5 5 | | mW |
| Luminous Flux | Φ_V | DC Drive Current = 20 mA DC Drive Current = 30 mA DC Drive Current = 50 m | | 250 325 450 | | mlm |
| Forward Voltage | V_F | DC Drive Current = 20 mA DC Drive Current = 30 mA DC Drive Current = 50 mA | | 3.5 3.9 4.5 | 3.9 | V |
| Reverse Leakage Current | I_R | Reverse Voltage = 5 V | | | 10 | μA |

- Change in Radiant Intensity with temperature $-1.4\mu\text{W/sr}/^\circ\text{C}$ ($25^\circ\text{C} < \text{temp} < 85^\circ\text{C}$)
- Change in Radiant Intensity with temperature $0.7\mu\text{W/sr}/^\circ\text{C}$ ($25^\circ\text{C} < \text{temp} < -40^\circ\text{C}$)

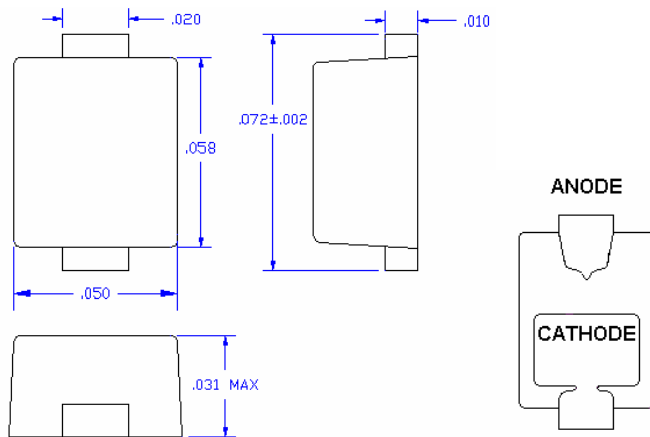
DIRECTIVITY

Polar plot of angular Intensity %



Relative Angular Intensity

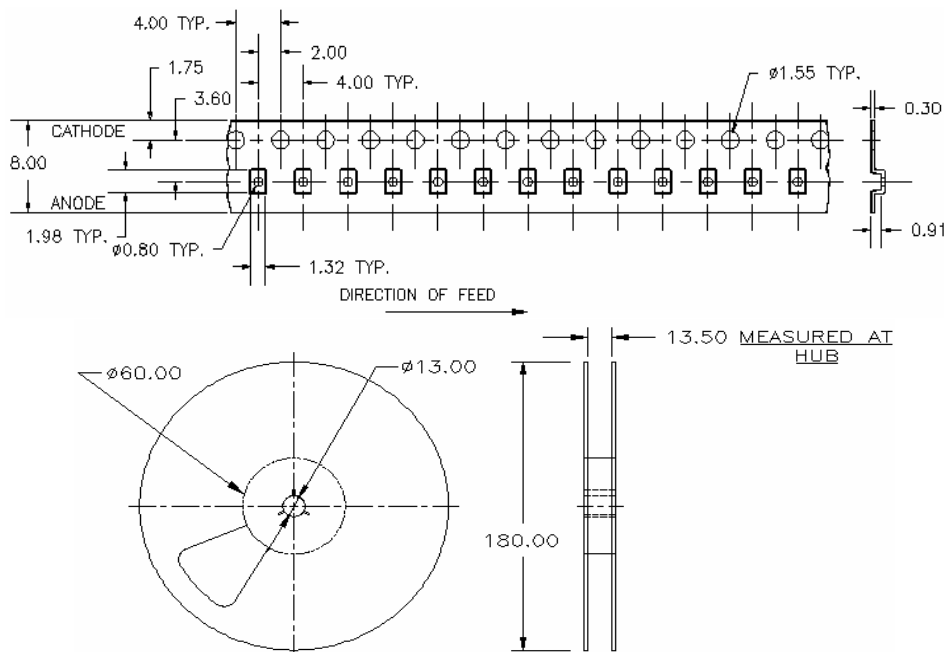
Typical UPBLED470B

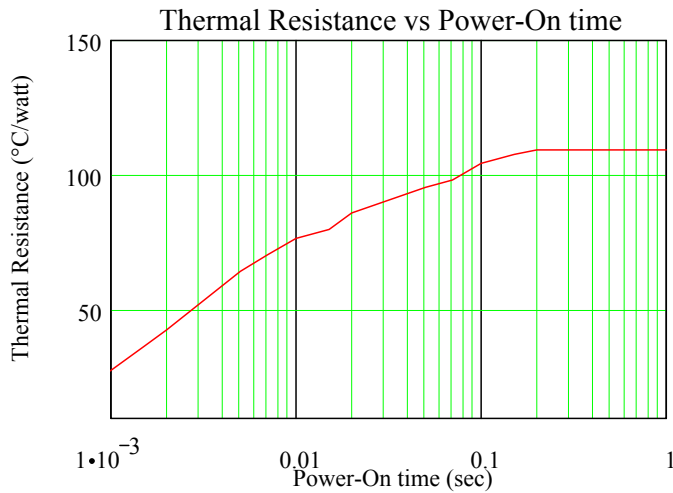

BOTTOM VIEW

- Notes:
- Anode is identified by observing the underside of the LED.
(Anode is the smaller of the two base pads)
 - Mount to circuit board using 60/40 Pb/Sn or equivalent.
 - Maximum solder melt exposure temperature is 225°C for 10 seconds.

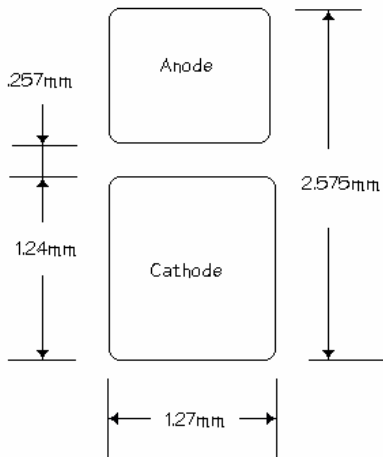
TAPE AND REEL
3,000 units/reel

Notes: Dimensions is shown in metric.

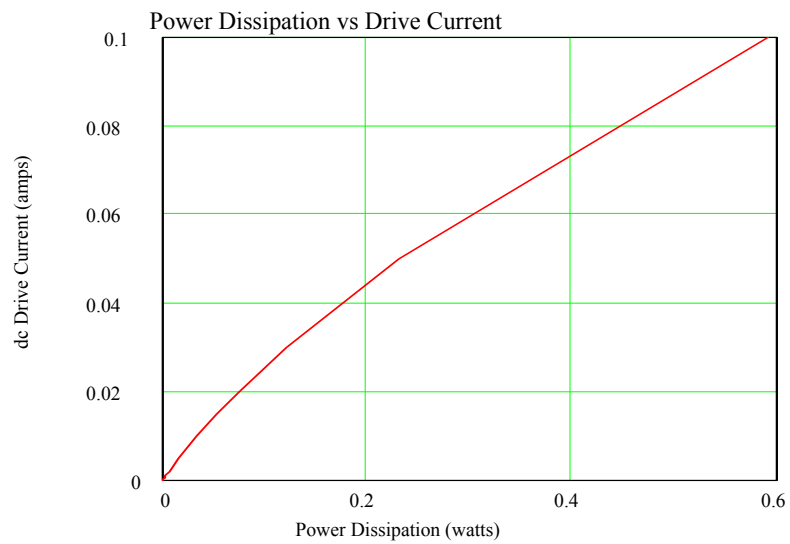
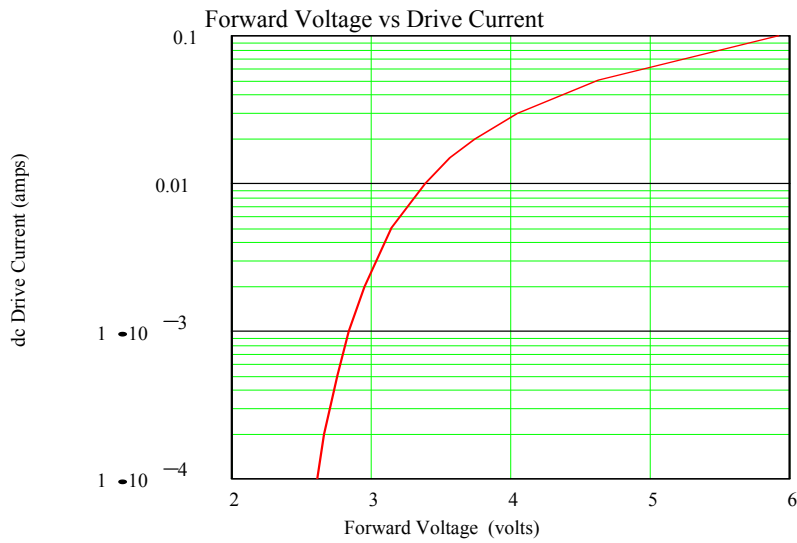




Steady State Thermal Resistance Junction-to-Optomite base metal ~ 110°C/W
 Thermal time constant ~ 20 mS (@ 0.632 x R_{0max}).
 Steady state temperature at ~ 500 mS.



Mounting footprint, Copper (note: Silver plating will enhance Luminous Intensity)





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CALCULATION FOR SAFE OPERATION ABOVE 20 ma dc:

The power dissipation must be held at a level to maintains the junction below the maximum specified operating temperature.

Duty cycle control may be used to establish the safe operating condition using a train of pulses.

LED Junction temperature may be calculated by use of the following:

$$T_J := T_{Case} + V_F \cdot I_{Dpk} \left[\frac{t_p \cdot R_{\theta JS}}{\tau} + \left(1 - \frac{t_p}{\tau} \right) \cdot Z_{\theta_{\tau+t_p}} - Z_{\theta_{\tau}} + Z_{\theta_{tp}} \right]$$

T_{Case} is at a specified temperature. V_F and I_{Dpk} values are read off graph of forward voltage vs drive current. t_p and τ are set by the on-time and pulse period of the drive circuit. Thermal Impedances (Z_{θ}) and Thermal resistance (R_{θ}) values are read from Thermal Impedance graph.

Conversion of 1931 x y coordinates to 1960 u v coordinates:

$$u = 4x/(-2x + 12y + 3), \quad v = 6y/(-2x + 12y + 3)$$

Conversion of 1960 u v coordinates to 1931 x y coordinates:

$$x = 3u/(2u - 8v + 4), \quad y = 2v/(2u - 8v + 4).$$

* UPBLED-470B SPICE MODEL

```
.model UPBLED-470B D(Is=1E-30 N=1.923 Rs=32 Ikf=42.04 Eg=3.6 Cjo=63.87p
+      M=.1513 Vj=2.02 Fc=.5 Isr=1.3m Nr=3.4Meg Bv=12 Ibv=369.5u
+      Tt=432.8n Xti=5)
```